Silicon P-Channel MOS FET

HITACHI

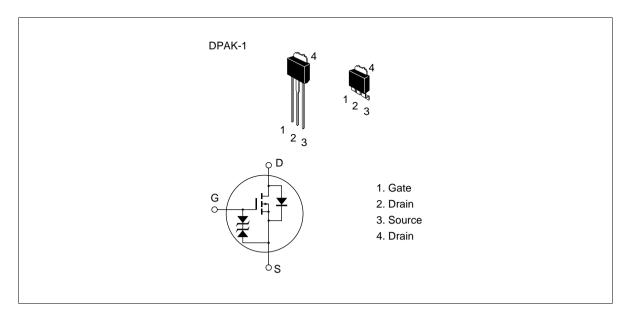
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator and DC-DC converter

Outline







Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DSS}	-600	V	
Gate to source voltage	V _{GSS}	±15	V	
Drain current	I _D	-0.5	А	
Drain peak current	I *1 D(pulse)	-1.0	A	
Body to drain diode reverse drain current	I _{DR}	-0.5	А	
Channel dissipation	Pch*2	20	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

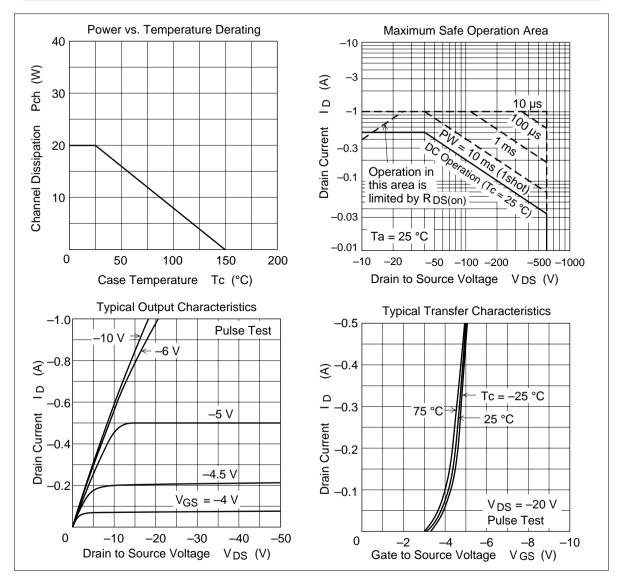
Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

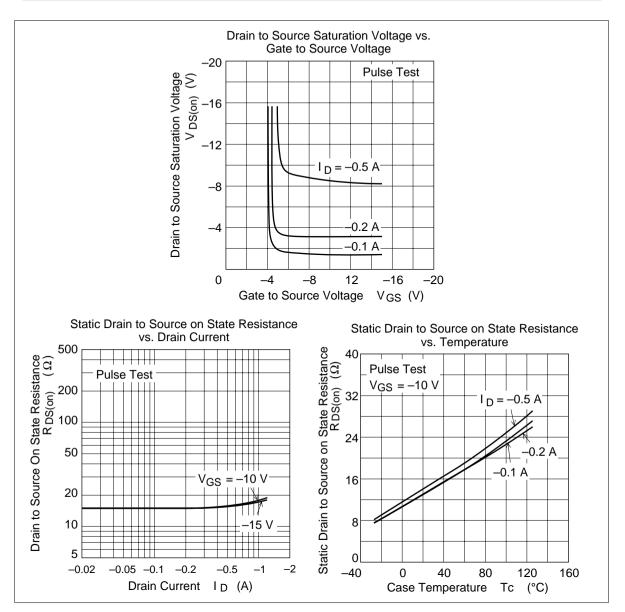
2. Value at $T_c = 25^{\circ}C$

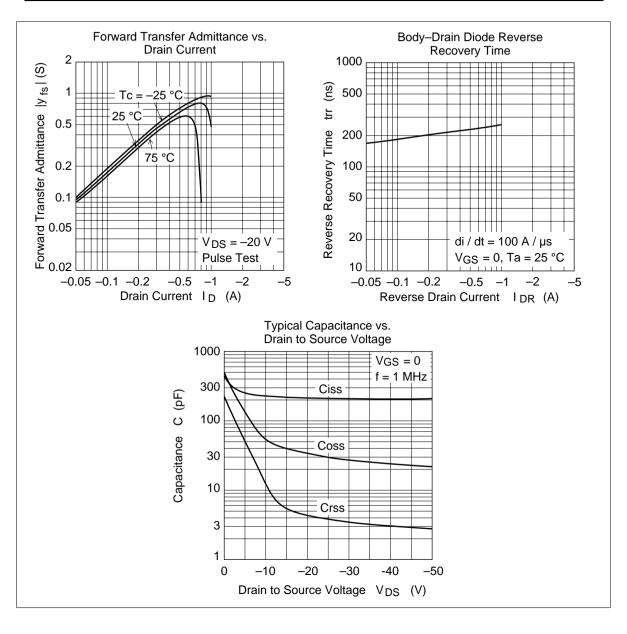
Electrical Characteristics ($Ta = 25^{\circ}C$)

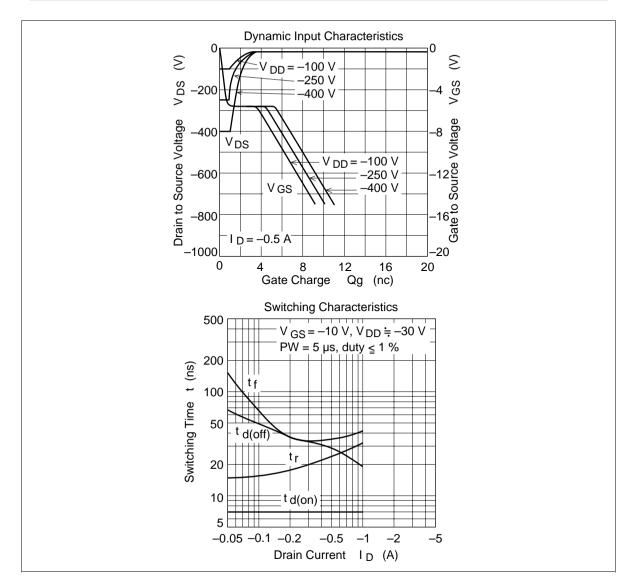
Item	Symbol	Min	Тур	Max	Unit	Test conditions	
Drain to source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	-600	_	_	V	$I_{\rm D} = -10$ mA, $V_{\rm GS} = 0$	
Gate to source breakdown voltage	$V_{(BR)GSS}$	±15	—	—	V	$I_{g} = \pm 100 \ \mu A, \ V_{DS} = 0$	
Gate to source leak current	I _{GSS}	_		±10	μΑ	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0$	
Zero gate voltage drain current	I _{DSS}	_		-100	μΑ	$V_{\rm DS} = -500 \text{ V}, \text{ V}_{\rm GS} = 0$	
Gate to source cutoff voltage	$V_{GS(off)}$	-2.0		-4.0	V	$I_{\rm D} = -1 \text{ mA}, V_{\rm DS} = -10 \text{ V}$	
Static drain to source on state resistance	$R_{\text{DS(on)}}$	—	15	25	Ω	$I_{\rm D} = -0.3$ A, $V_{\rm GS} = -10$ V ^{*1}	
Forward transfer admittance	y _{fs}	0.3	0.45	_	S	$I_{\rm D} = -0.3 \text{ A}, V_{\rm DS} = -20 \text{ V}^{*1}$	
Input capacitance	Ciss	—	220		pF	$V_{DS} = -10 V, V_{GS} = 0,$	
Output capacitance	Coss	—	55		pF	f = 1 MHz	
Reverse transfer capacitance	Crss	—	13		pF		
Turn-on delay time	t _{d(on)}	_	7	_	ns	$I_{\rm D} = -0.3 \text{ A}, V_{\rm GS} = -10 \text{ V},$	
Rise time	t _r	—	20		ns	$R_{L} = 100 \Omega$	
Turn-off delay time	$t_{d(off)}$	_	35	_	ns		
Fall time	t _f	_	35	_	ns		
Body to drain diode forward voltage	V_{DF}	—	-0.85	—	V	$I_{F} = -0.5 \text{ A}, V_{GS} = 0$	
Body to drain diode reverse recovery time	t _{rr}	_	230	—	ns	$I_{_{\rm F}} = -0.5$ A, $V_{_{\rm GS}} = 0$, $di_{_{\rm F}}/dt = 50$ A/ μ s	

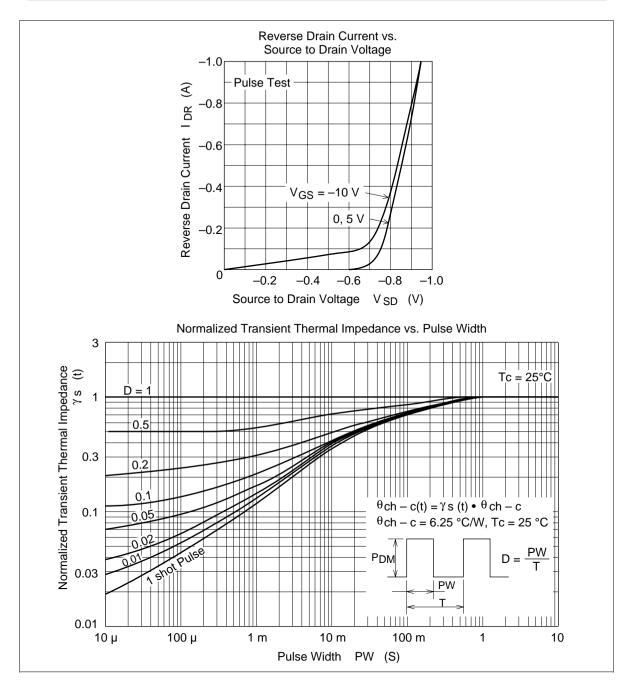
Note: 1. Pulse test

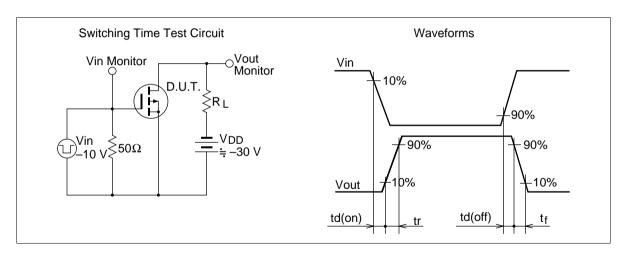




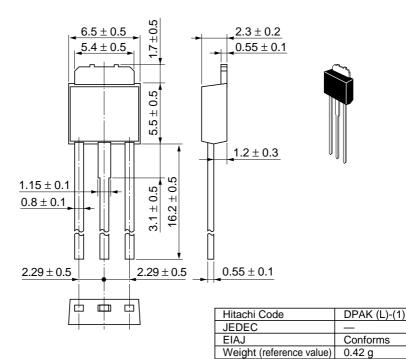








Unit: mm



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